



The products are voltage opto-couplers in a VSON4 package. The device consists of a high-voltage output detector circuit. It is capable of directly driving gates of power MOSFETs or IGBTs. The products are widely used in supply for electronic circuit and drive solid state relay.

High isolation 500 VRMS

Operating temperature range -40°C to 110°C

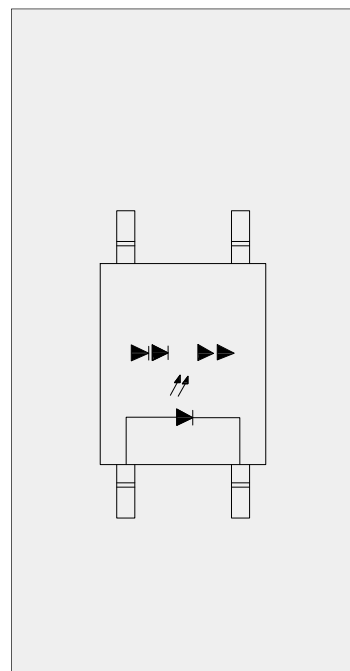
RoHS & REACH Compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved



(Temperature=25°C)

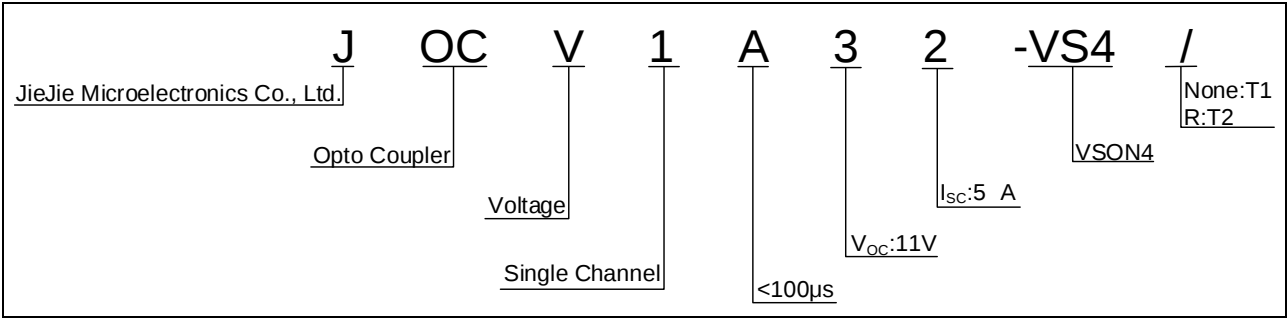
Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	75	mW
Isolation Voltage		V_{iso}	500	Vrms
Operating Temperature		T_{opr}	-40~+110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~+125	
Soldering Temperature		T_{sol}	260	

μ



(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10\text{mA}$	-	1.8	2.5	V
	Reverse Current	I_R	$V_R=6\text{V}$	-	-	1	μA
Output	Open Circuit Voltage	V_{OC}	$I_F=10\text{mA}$ $I_O=0\text{mA}$	11	-	-	V
	Short Circuit Current	I_{SC}	$I_F=10\text{mA}$ $V_O=0\text{V}$	5	-	-	μA
Transfer Characteristics	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	-	-	Ω
	Response Time	t_{on}	$I_F=10\text{mA}$	-	100	-	μs
		t_{off}		-	50	-	μs



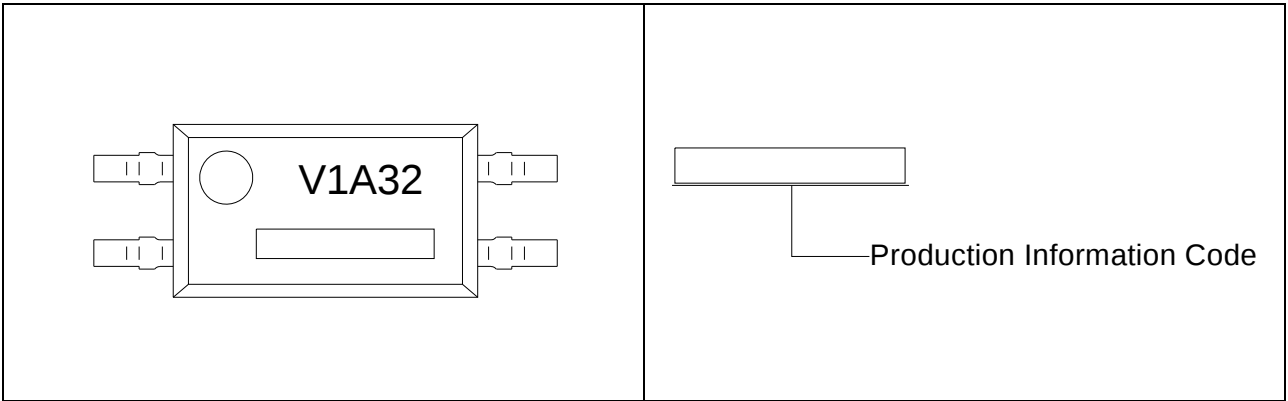
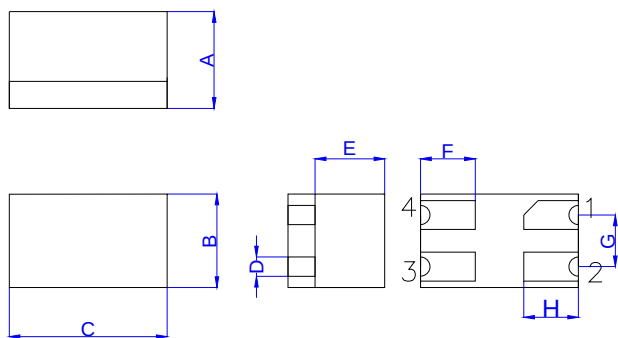
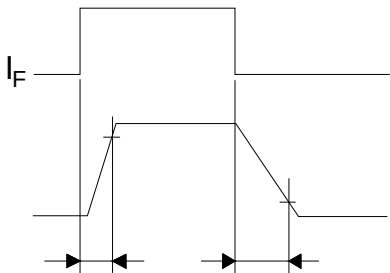
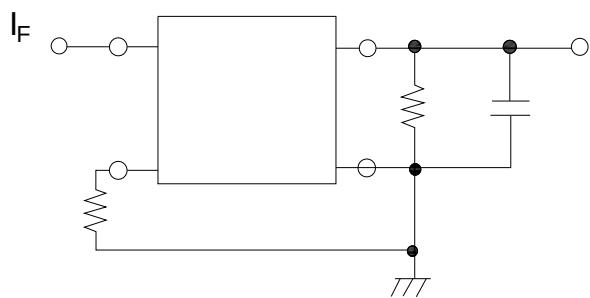




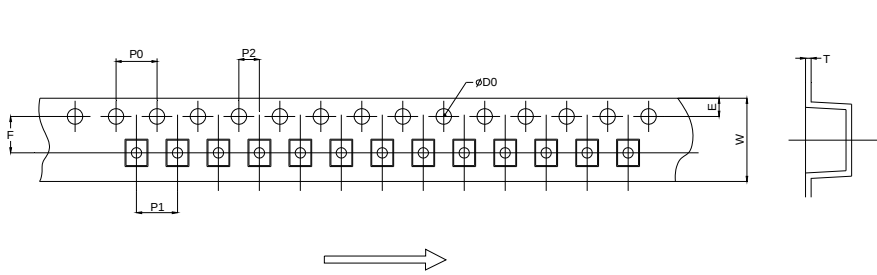
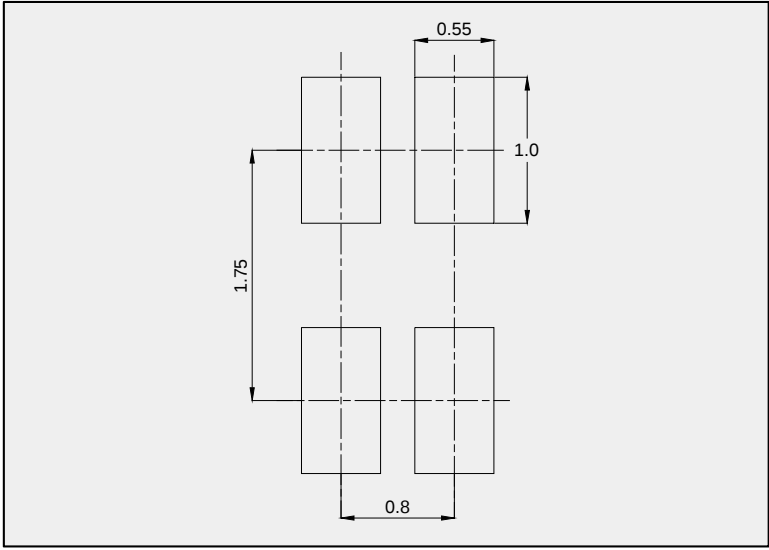
FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.2: Forward Current vs. Forward Voltage

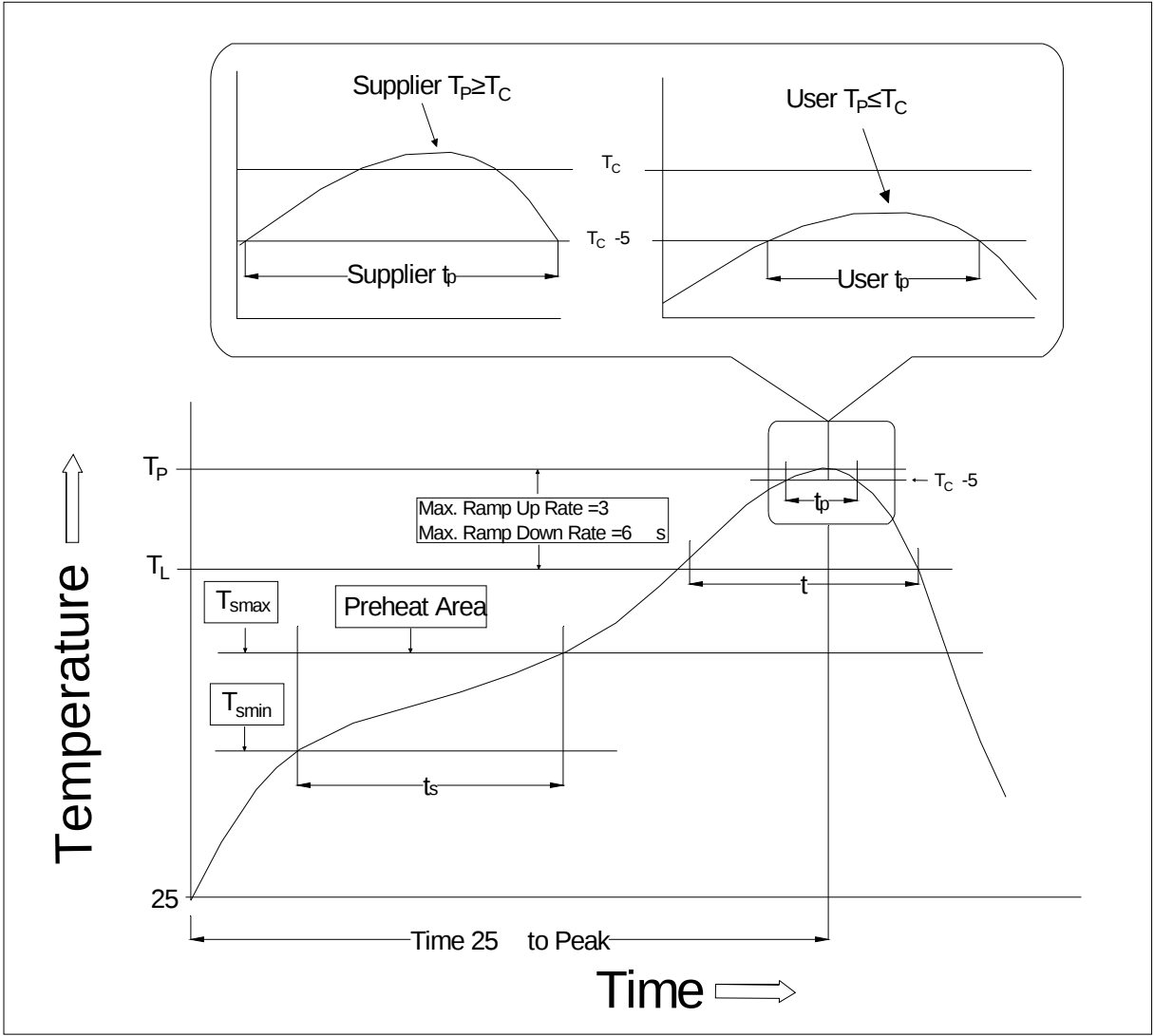
FIG.7: Response Time Test Circuit, Waveform



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	1.30		1.70	0.051		0.067
B	1.25		1.65	0.049		0.065
C	2.25		2.65	0.089		0.104
D	0.10		0.50	0.004		0.020
E	0.88		1.28	0.035		0.050
F	0.65		1.05	0.026		0.041
G	0.60		1.00	0.024		0.039
H	0.65		1.05	0.026		0.041



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	3.90	4.00	4.10	0.154	0.157	0.161
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	3.40	3.50	3.60	0.134	0.138	0.142
T	0.20	0.25	0.30	0.008	0.010	0.012
W	7.70	8.00	8.30	0.303	0.315	0.327



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150
Temperature Max. (T _{smax})	150	200
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3 °C/second max.	3 °C/second max.
Liquidus Temperature (T _L)	183	217
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t _P) within 5 °C of 260	10 seconds	10 seconds
Ramp-down Rate (T _P to T _L)	3-6 °C/second	3-6 °C/second
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 3

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